# AEC-Q200

### FENG-JUI TECHNOLOGY CO., LTD

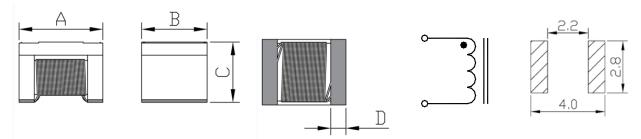
## F2P322523NVQ1 TYPE

#### **FEATURE**

- Ensuring consistent high quality and reliability as the result of a completely automated manufacturing process
- 2. Operating temperature range: –55 to +125°C (including self-temperature rise)
- 3. Same as MURATA LQW32FTxxx type

#### Applications

- 1. Inductor for use with separate signal and power lines in in-vehicle PoC (Power Over Coax)
- 2. Compliant with AEC-Q200
- Shape and Dimension and Schematics and Land Patterns(mm)



A= 3.20±0.20 m/m; B=2.50±0.20 m/m; C=2.30±0.20 m/m; D=0.58±0.20 m/m

#### Specification

PART NO.	INDUCTANCE (uH)	DCR (Ω) MAX	Isat (mA)	Itemp (mA) At 85°C	Itemp (mA) at 105°C	Itemp (mA) at 125°C
F2P322523NVQ1 -4R7M	4.7uH±20%	0.28	850	850	720	400
F2P322523NVQ1 -470M	47uH±20%	0.90	300	500	300	100

Note1. Measurement ambient temperature of electrical: at 25°C

Note2. Test equipment: HP4294A, 1MHz, 0.25V

Note3. Isat: when based on the inductance change rate (30% below the nominal inductance value)

Note4. Itemp: When based on the temperature increase (temperature increase of 40°C by self heating)

Note5.Packaging: Taping; Quantity: 1500 Pieces/reel



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#### GENERAL CHARACTERISTICS

- 1. Operating temperature range: -55 TO + 125°C (Includes temperature when the coil is heated)
- 2. High temperature exposure(storage) refer MIL-STD-202 Method 108: 1000 hrs at rated operating temperature(e.g. 125°C). Part can be stored for 1000 hrs @125°C. Unpowered. Measurement at 24±4 hours after test conclusion.
- 3. Temperature cycling refer JESD22 Method JA-104: 1000 cycles(-55 TO + 125℃). Measurement at 24±4 hours after test conclusion. 30 min maximum dwell time at each temp. extreme. 1 min. maximum transition time.
- 4. Biased Humidity refer MIL-STD-202 Method 103: 1000 hours 85°C/85%RH. Unpowered. Measurement at 24±4 hours after test conclusion.
- 5. Operational Life refer MIL-PRF-27: 1000 hrs. at 125 °C tested. Measurement at 24±4 hours after test conclusion.
- 6. External Visual refer MIL-STD-883 Method 2009: Inspect device construction, marking and workmanship.
- Physical Dimension refer JESD22 Method JB-100: Verify physical dimensions to the applicable device detail specification.
- 8. Resistance to Solvents refer MIL-STD-202 Method 215: Add aqueous wash chemical OKEM clean or equivalent.
- 9. Mechanical Shock refer MIL-STD-202 Method 213: Figure 1 of Method 213. Condition C.
- 10. Vibration refer MIL-STD-202 Method 204: 5g;s for 20 minutes, 12 cycles each of 3 orientations. Test from 10-2000 Hz.
- 11. Resistance to soldering Heat refer MIL-STD-202 Method 210: Condition B No pre-heat of samples. Single wave solder-procedure 2 for SMD and procedure 1 for leaded with solder within 1.5mm of device body.
- 12. ESD refer AEC-Q200-002 or ISO/DIS 10605: Direct contact discharge 2kV.
- 13. Solderability refer J-STD-002: For both Leaded & SMD. Magnification 50X. Conditions: Leaded, Method A@235℃, category 3; SMD, a)Method B, 4hrs@125℃ dry heat @235℃, b)Method B@215℃ category 3., c)Method D category 3@260℃
- 14. Electrical Characterization refer spec: Show Min, Max Mean and Standard deviation at room from Min and Max temperature.
- 15. Flammability refer UL-94: V-0 or V-1 Acceptable.
- 16. Board Flex refer AEC-Q200-005: 60 sec minimum holding time.
- 17. Terminal Strength(SMD) refer AEC-Q200-006
- 18. Reflow profile recommend:

